

ABSTRACT OF THE DISCLOSURE

A heat-peelable pressure-sensitive adhesive sheet for electronic parts which after a heat treatment can be easily peeled from the electronic parts while causing little contamination is disclosed. The heat-peelable pressure-sensitive adhesive sheet for electronic parts which has a heat-expandable layer containing heat-expandable microspheres and a non-heat-expandable pressure-sensitive adhesive layer formed on at least one side of the heat-expandable layer, wherein when the pressure-sensitive adhesive sheet is applied, on the side of the non-heat-expandable pressure-sensitive adhesive layer, to a surface of a silicon wafer and is thereafter heated and peeled from the wafer, then the carbon element proportion R_{C1} (%) on this silicon wafer surface satisfies at least either of the following relationships (1) and (2): $R_{C1} \leq 50 + R_{C2}$ (1); $R_{C1} \leq 2.5R_{Si}$ (2), wherein R_{C2} represents the carbon element proportion (%) on the silicon wafer surface before the application; and R_{Si} represents the silicon element proportion (%) on the silicon wafer surface after the non-heat-expandable pressure-sensitive adhesive layer applied to the silicon wafer surface is heated and peeled therefrom.



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